# NEC'S 6-PIN DIP 400 V BREAK DOWN VOLTAGE 1-CH OPTICAL COUPLED MOS FET

# PS7142-1A PS7142L-1A

## FEATURES

CEI

- 1 CHANNEL TYPE: 1 a Output
- LOW LED OPERATING CURRENT: IF= 2mA
- DESIGNED FOR AC/DC SWITCHING LINE CHANGER
- SMALL PACKAGE: 6-Pin DIP
- LOW OFFSET VOLTAGE
- PS7142L-1A:
  Surface mount type
- SAFETY STANDARDS: UL approved: File No. E72422 (S) BSI approved: File No. 8245/8246

CSA approved: File No. CA 101391

## DESCRIPTION

NEC's PS7142-1A and PS7142L-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

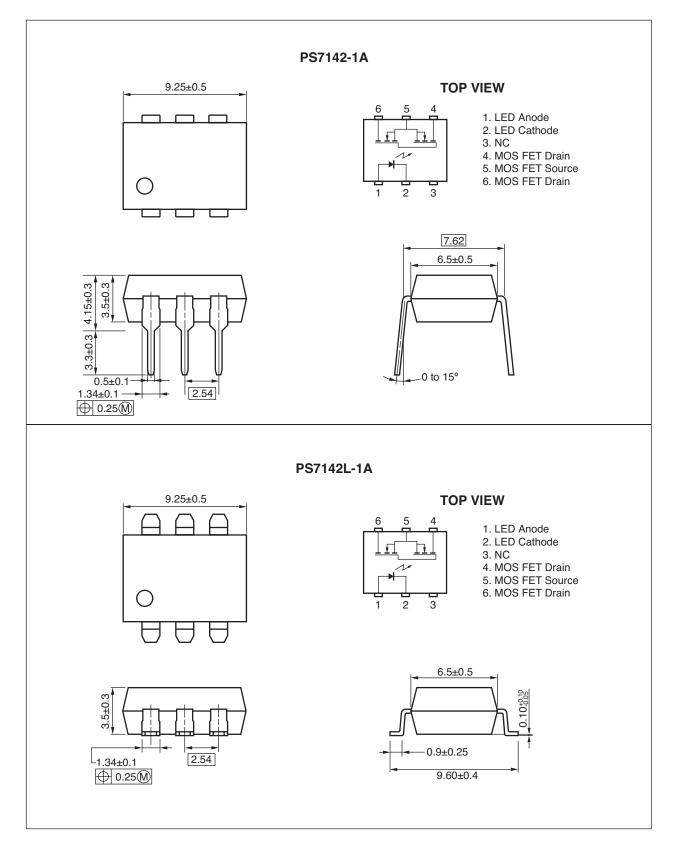
The PS7142L-1A has a surface mount type lead.

## **APPLICATION**

- Exchange Equipment
- Measurement Equipment
- FA/OA Equipment

California Eastern Laboratories

## PACKAGE DIMENSIONS (UNIT: mm)



# **ORDERING INFORMATION (Pb-Free)**

PART NUMBER	PACKAGE	PACKING STYLE	APPLICATION PART NUMBER *1
PS7142-1A-A	6-pin DIP	Magazine case 50 pcs	PS7142-1A
PS7142L-1A-A			PS7142L-1A
PS7142L-1A-E3-A		Embossed Tape 1000 pcs/reel	
PS7142L-1A-E4-A			

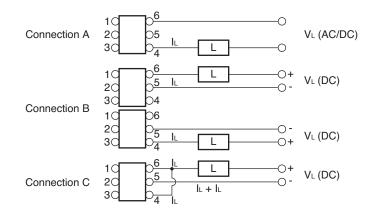
\*1 For the application of the Safety Standard, following part number should be used.

	PARAMETER		SYMBOL	RATINGS	UNIT
Diode	Forward Current (DC)		lF	50	mA
	Reverse Voltage		VR	5.0	V
	Power Dissipation		PD	50	mW
	Peak Forward Current*1		IFP	1	A
MOS FET Break Down Vol		e	VL	400	V
	Continuous Load Current *2	Connection A	IL I	200	mA
		Connection B		250	1
		Connection C		400	1
	Pulse Load Current *3		ILP	400	mA
	(AC/DC Connection)				
	Power Dissipation		PD	560	mW
Isolation Voltage *4			BV	1 500	Vr.m.s.
Total Power Dissipation			Рт	610	mW
Operating Ambient Temperature			TA	-40 to +85	°C
Storage Temperature			Tstg	-40 to +100	°C

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise Specified)

\*1 PW = 100  $\mu$ s, Duty Cycle = 1 %

\*2 Conditions: IF  $\geq$  2 mA. The following types of load connections are available.



\*3 PW = 100 ms, 1 shot

\*4 AC voltage for 1 minute at T\_A = 25 °C, RH = 60 % between input and output

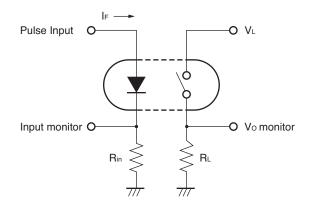
			`		/
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

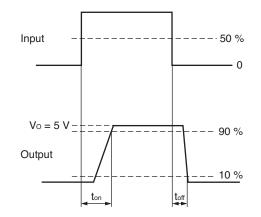
# **RECOMMENDED OPERATING CONDITIONS** (TA = 25°C)

# **ELECTRICAL CHARACTERISTICS** (TA = 25°C)

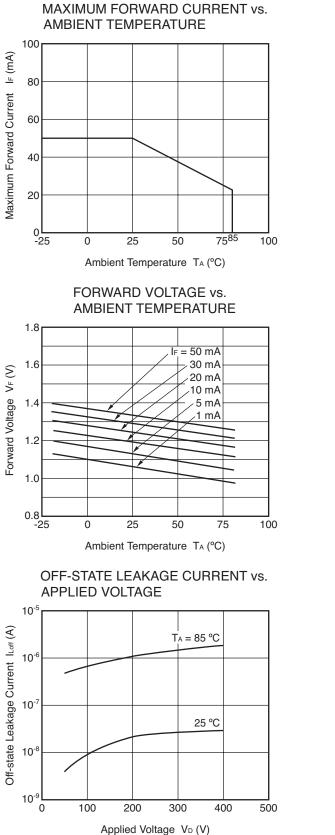
PARAMETER		SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Diode	Forward Voltage	VF	I⊧ = 10 mA		1.2	1.4	V
	Reverse Current	IR	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V <sub>D</sub> = 400 V		0.03	1.0	μA
	Output Capacitance	Cout	V <sub>D</sub> = 0 V, f = 1 MHz		225		pF
Coupled	LED On-state Current	IFon	l∟ = 200 mA			2.0	mA
	On-state Resistance	Ron1	I⊧ = 10 mA, I∟ = 10 mA		6.0	10	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 200 \text{ mA}, t \le 10 \text{ ms}$	]			
	Turn-on Time <sup>*1</sup>	ton	I⊧ = 10 mA, V₀ = 5 V, R∟ = 500 Ω,		0.8	5.0	ms
	Turn-off Time *1	toff	PW ≥ 10 ms		0.02	0.2	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 <sup>9</sup>			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		1.1		pF

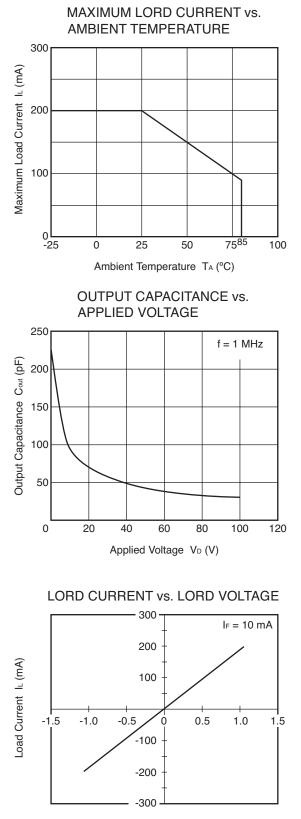
\*1 Test Circuit for Switching Time



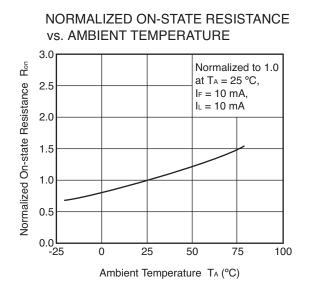


### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

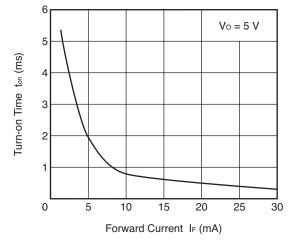




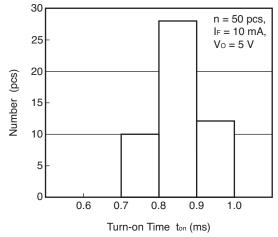
Load Voltage VL (V)



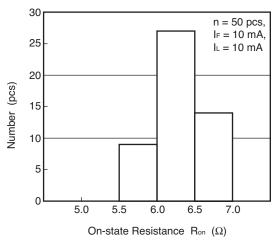
#### TURN-ON TIME vs. FORWARD CURRENT



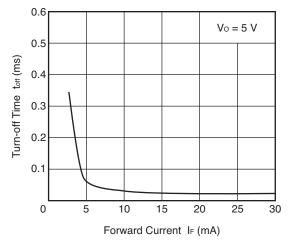


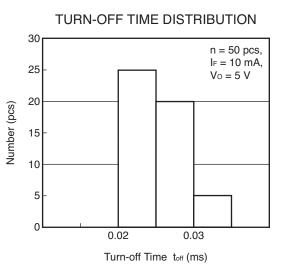


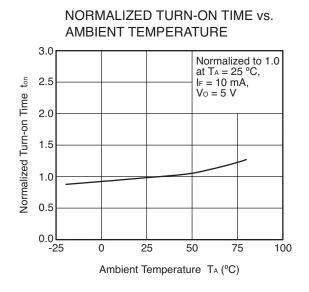
**ON-STATE RESISTANCE DISTRIBUTION** 

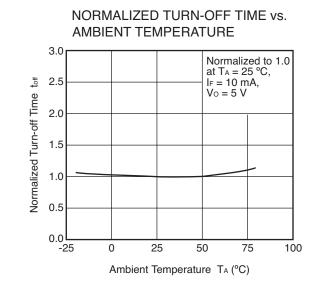


#### TURN-OFF TIME vs. FORWARD CURRENT



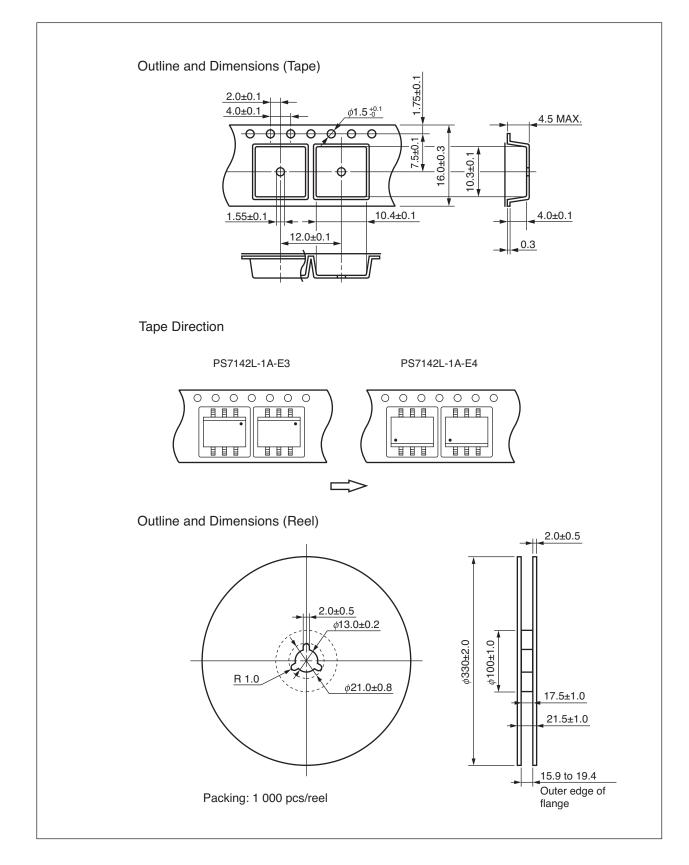






Remark The graphs indicate nominal characteristics.

### TAPING SPECIFICATIONS (UNIT:mm)



#### **RECOMMENDED SOLDERING CONDITIONS**

#### (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature
  10

10 seconds or less

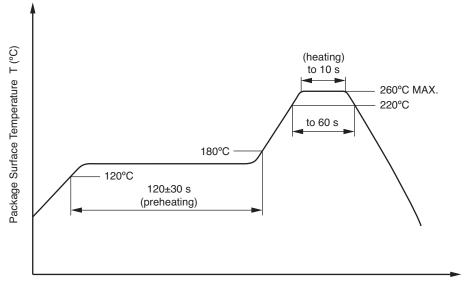
- Time of temperature higher than 220°C
  60 seconds or less
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow

120±30 s

Three





#### (2) Wave soldering

Temperature 260°C or below (molten solder temperature)

One

- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
  - Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (3) Cautions

• Flux

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
РВВ	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

See CEL Terms and Conditions for additional clarification of warranties and liability.

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